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HEMT-3301/HEMT-1001 940 nm High Radiant Emitters

Data Sheet

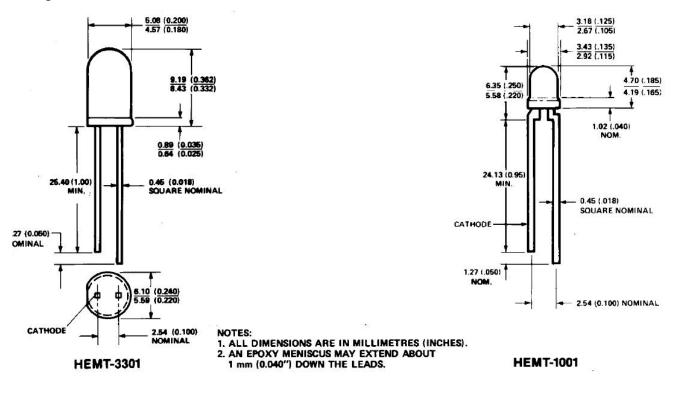


Description

The HEMT-3301 and HEMT-1001are infrared emitters, using amesa structure GaAs on GaAs infrared diode, IRED, optimized for maximum quantum efficiency at a peak wavelength of 940 nm. The HEMT-3301 and HEMT-1001emitters are untinted, undiffused plastic packages with medium wide radiation patterns. These medium-wide and wide radiation patterns eliminate the beam focusing problems that are encountered with emitters that have narrow radiation patterns. Applications include optical transducers, optical part counters, smoke detectors, covert identification, paper tape and card readers, and optical encoders.

Features

- Nonsaturating, High Radiant Flux Output
- Efficient at Low Currents, Combined with High Current Capability
- Three Package Styles
- Operating Temperature Range -40°C to +100°C
- Medium-Wide Radiation Patterns
- Radiated Spectrum Matches Response of Silicon
 Photodetectors



Package Dimensions

Absolute Maximum Ratings at $T_A = 25^{\circ}C$

Description	Min.	Тур.	Max.	Units	Notes
Power Dissipation		150		mW	
DC Forward Current		100		mA	Derate as specified in Figure 6
Peak Forward Current		1000		mA	Time average current as determined from Figure 7
IRED Junction Temperature		110		°C	
Operating Temperature	-40		+100	°C	
Storage Temperature	-40		+100	°C	
Lead Soldering Temperature		260		°C for 5 seconds	1.6 mm (0.063 in.) from emitter body

Electrical/Optical Characteristics at $T_{\text{A}} = 25^{\circ}\text{C}$

Symbol	Description	Min.	Тур.	Max.	Units	Test Conditions	Fig.
l _e	Radiant Intensity				mW/sr	I _F = 20 mA	4, 5
	HEMT-3301	2.5	4.0				
	HEMT-1001	1.0	2.0				
$\Delta I_{e} / \Delta T$	Temperature Coefficient for Radiant Intensity ^[1]		-0.58		%/°C	Measured at λ_{PEAK}	1
ΔΙ/ΔΤ	Temperature Coefficient for Peak Wavelength ^[2]		0.3		nm/°C	Measured at λ _{ΡΕΑΚ}	1
λ_{PEAK}	Peak Wavelength		940		nm	Measured at λ _{ΡΕΑΚ}	1
2θ _{1/2}	Half Intensity ^[3]				deg.	I _F = 20 mA	8
	Total Angle				5		9
	HEMT-3301		50				
	HEMT-1001		60				
t _r	Output Rise Time (10% to 90%)		1700		ns	$\lambda_{\text{PEAK}} = 20 \text{ mA}$	
t _f	Output Fall Time (90% to 10%)		700		ns	$\lambda_{PEAK} = 20 \text{ mA}$	
С	Capacitance		30		pf	$V_F = 0;$ f = 1 MHz	
VR	Reverse Breakdown Voltage	5.0			V	$I_R = 10 \text{ mA}$	
V _F	Forward Voltage		1.30	1.50	V	I _F = 100 mA	2
			1.15			$I_F = 20 \text{ mA}$	
Rθj-pin	Thermal Resistance				°C/W	IRED Junction	
	HEMT-3301		260			to to Cathode	
	HEMT-1001		290			Lead	

Notes:

1. Radiant intensity at ambient temperature $I_e(T_A) = I_e(25^{\circ}C) + (\Delta I_e/\Delta T) (T_A - 25^{\circ}C)/100$.

2. Peak wavelength at ambient temperature: $\lambda_{PEAK}(T_A) = \lambda_{PEAK}(25^{\circ}C) + (\Delta I/\Delta T) (T_A - 25^{\circ}C)$.

3. $\theta_{1/2}$ is the off-axis angle from emitter centerline where the radiant intensity is half the on-axis value.

4. Approximate radiant flux output within a cone angle of 2θ : $\phi_e(2\theta) = [\phi_e(\theta)/I_e(0)] I_e(T_A); \phi_e(\theta)/I_e(0)$ obtained from Figure 8 or 9.

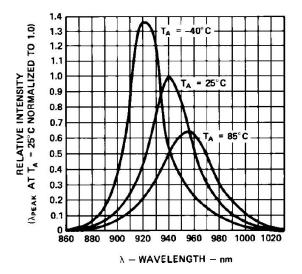


Figure 1. Radiated Spectrum.

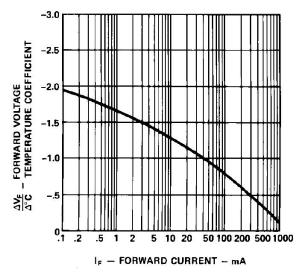


Figure 3. Forward Voltage Temperature Coefficient vs. Forward Current.

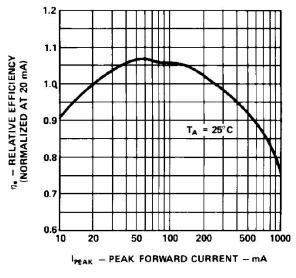


Figure 5. Relative Efficiency vs. Peak Forward Current.

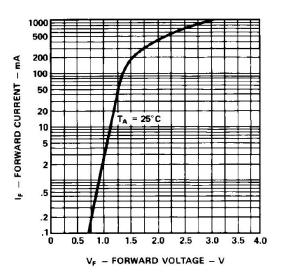


Figure 2. Forward Current vs. Forward Voltage.

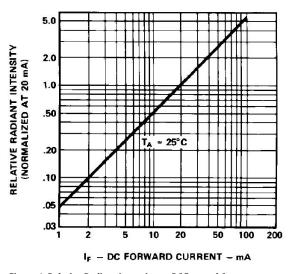


Figure 4. Relative Radiant Intensity vs. DC Forward Current.

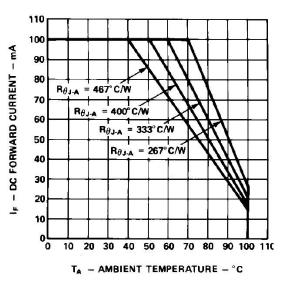


Figure 6. Maximum DC Forward Current vs. Ambient Temperature. Derating Based on $TJMAX = 110^{\circ}C$.

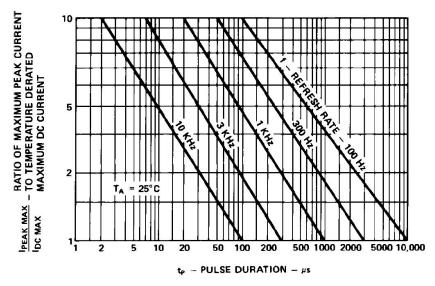


Figure 7. Maximum Tolerable Peak Current vs. Peak Determined from Temperature Derated IDC MAX).

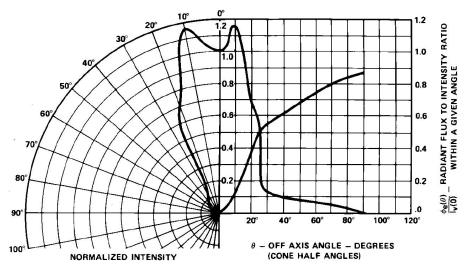


Figure 8. Far Field Radiation Pattern, HEMT-3301.

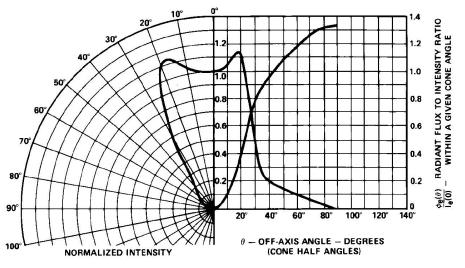


Figure 9. Far Field Radiation Pattern, HEMT-1001.

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